
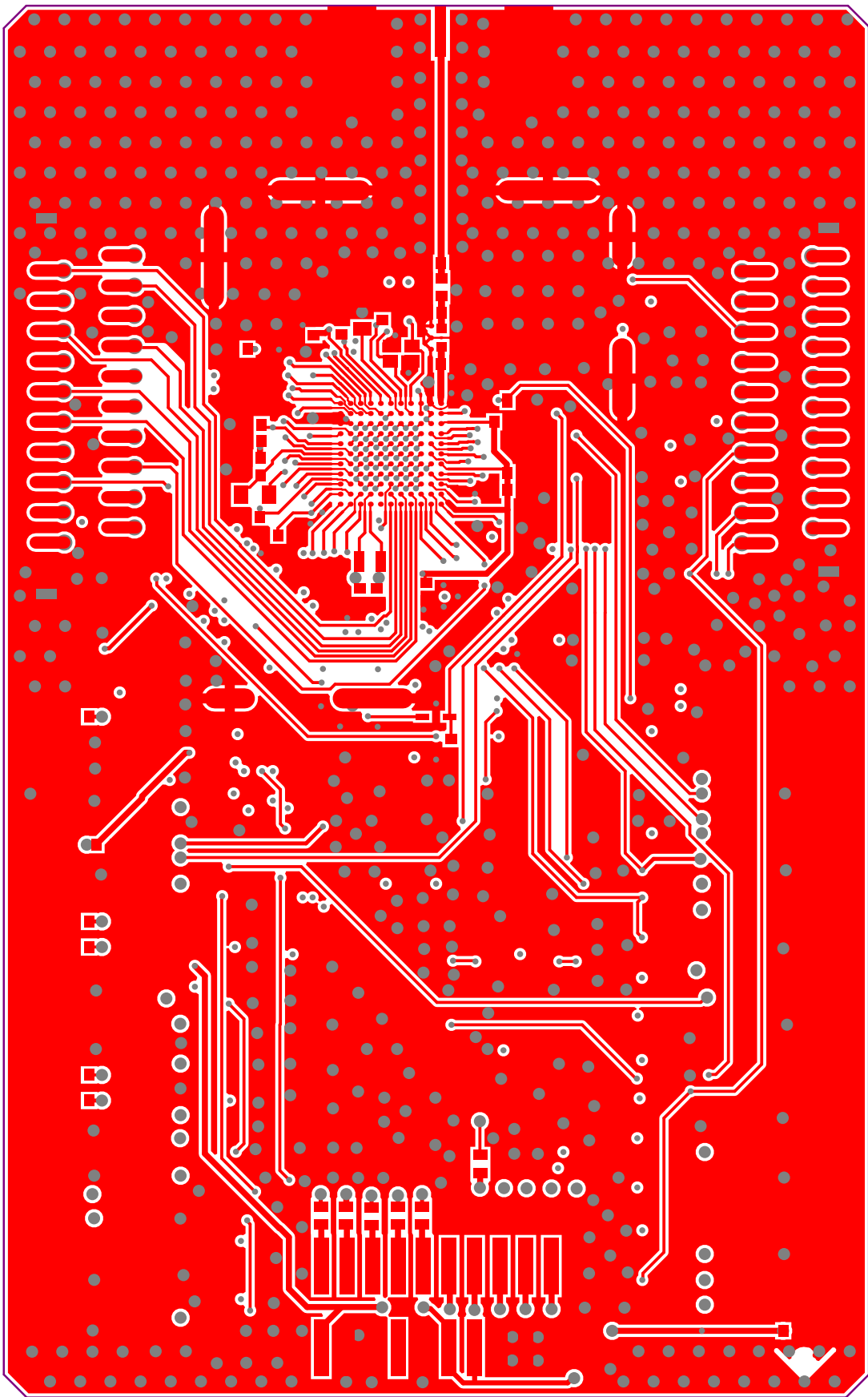

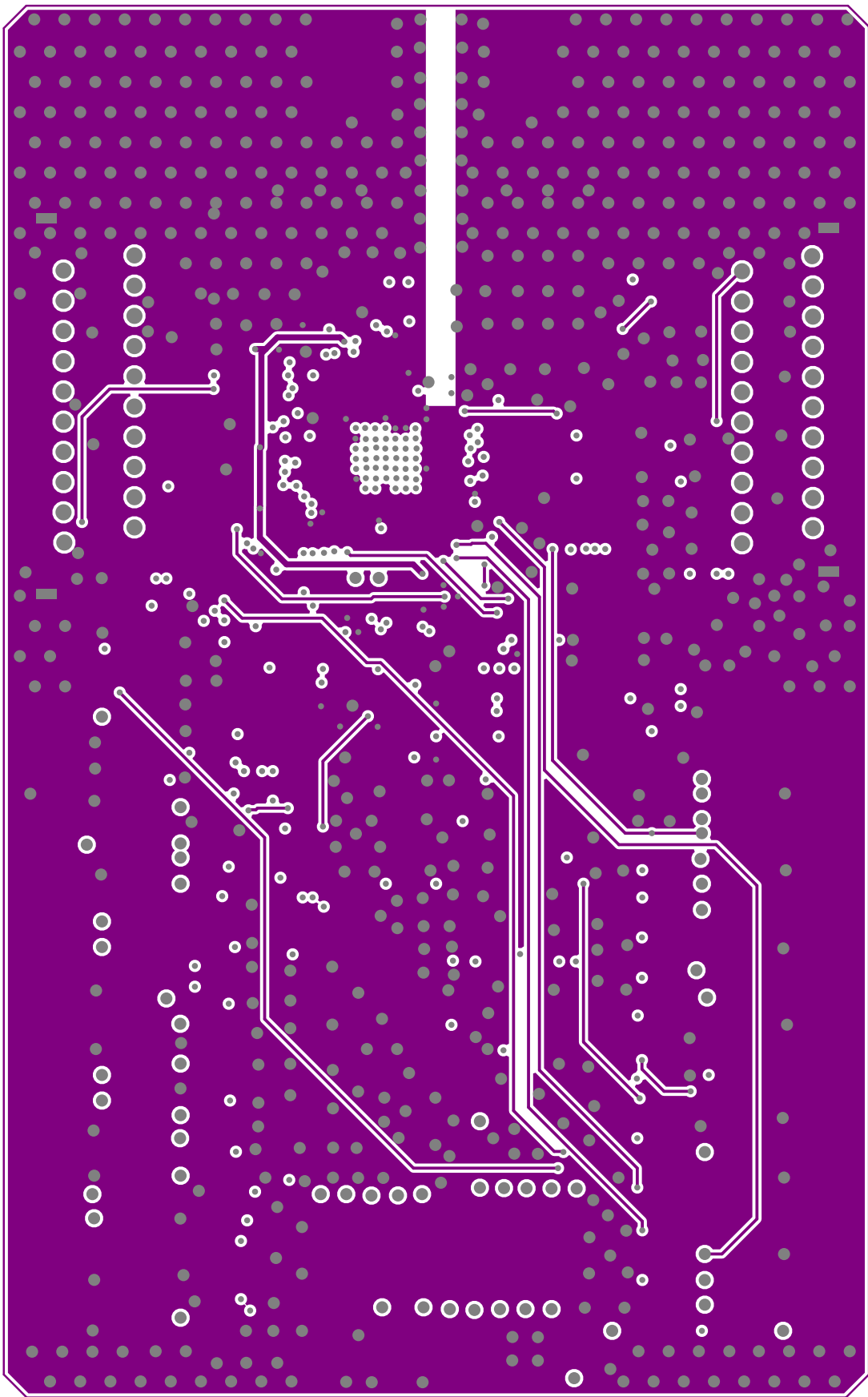



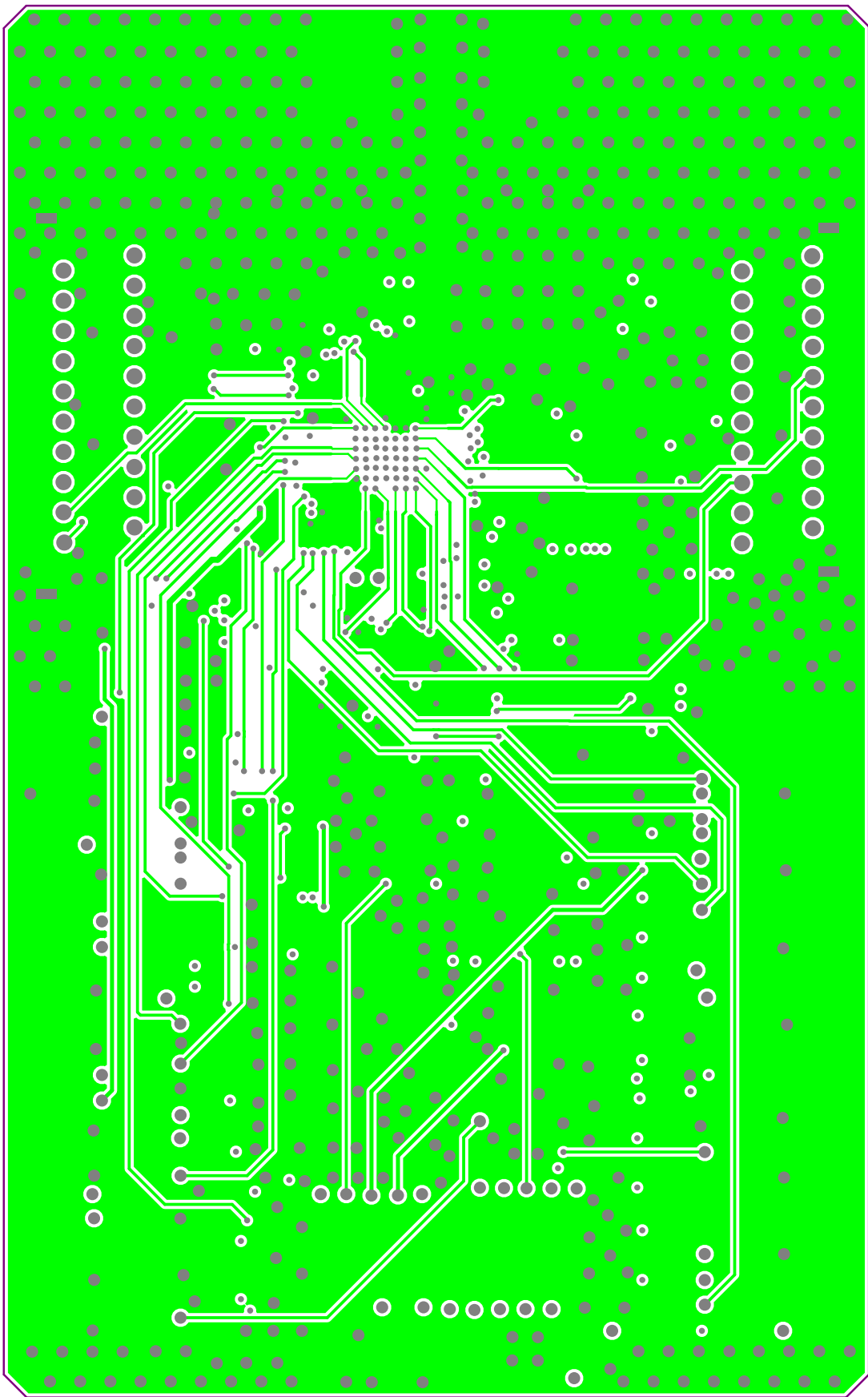
Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	




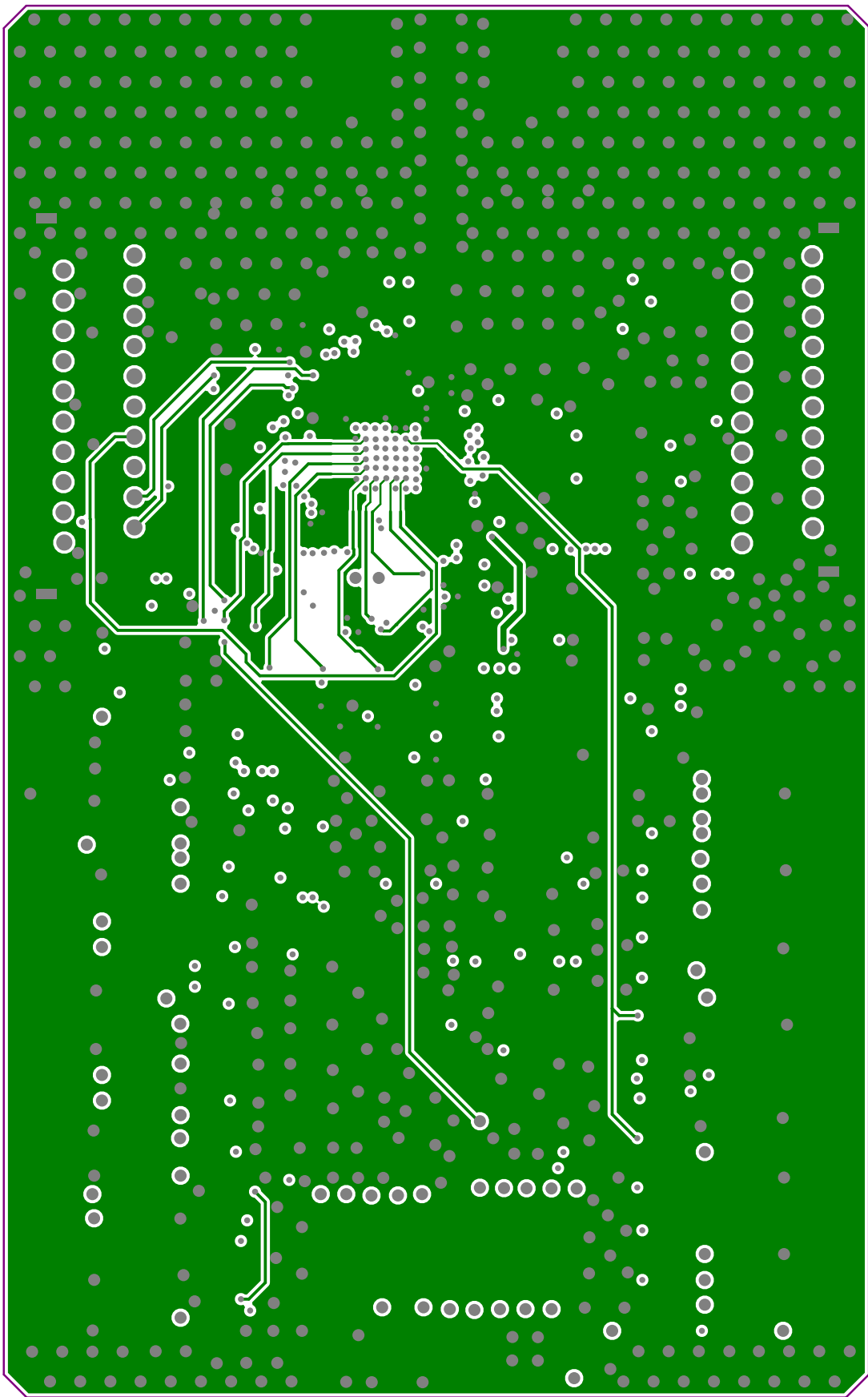
Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	




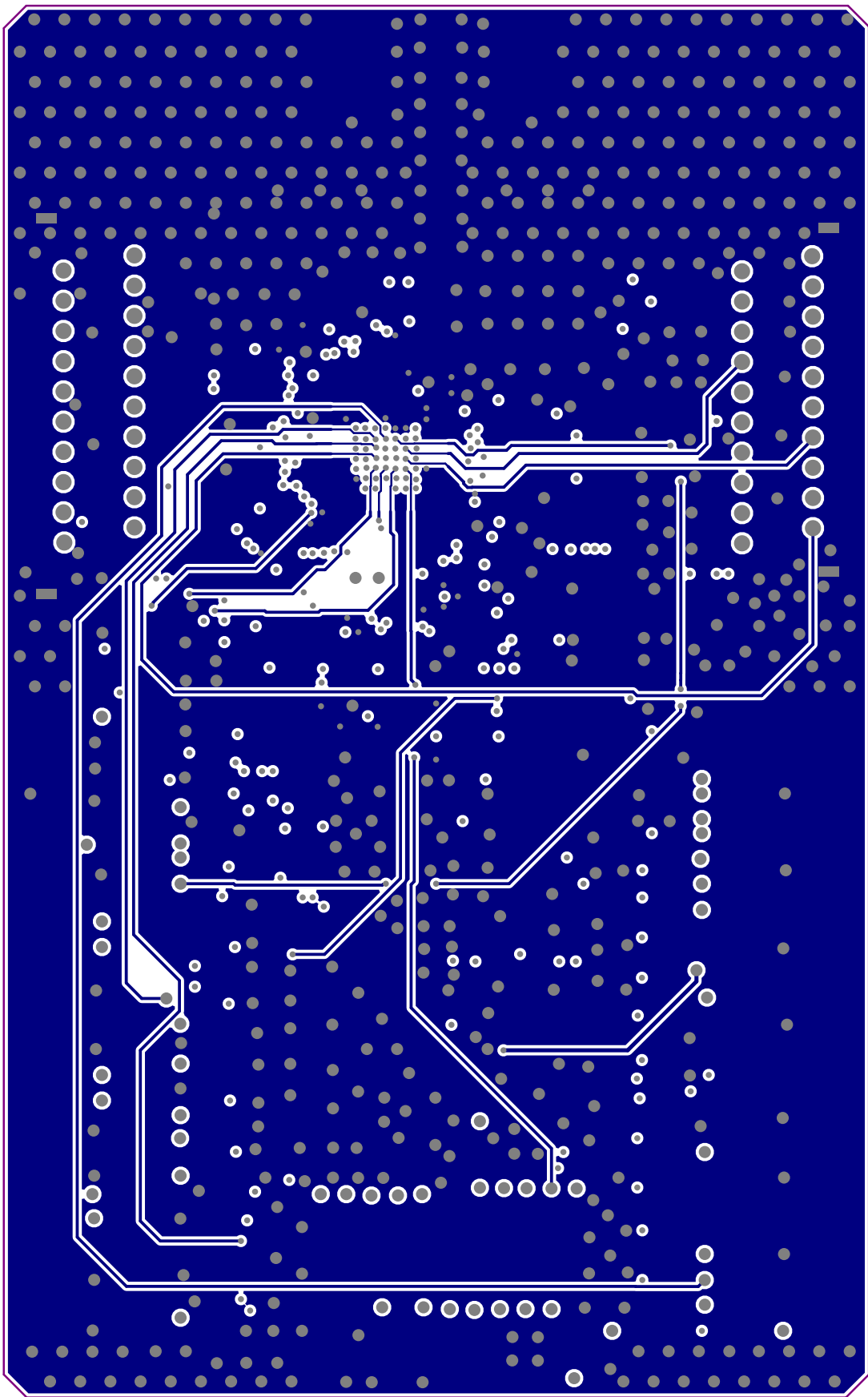
Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: Int1 (Sign)	Gerber: .G1	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	




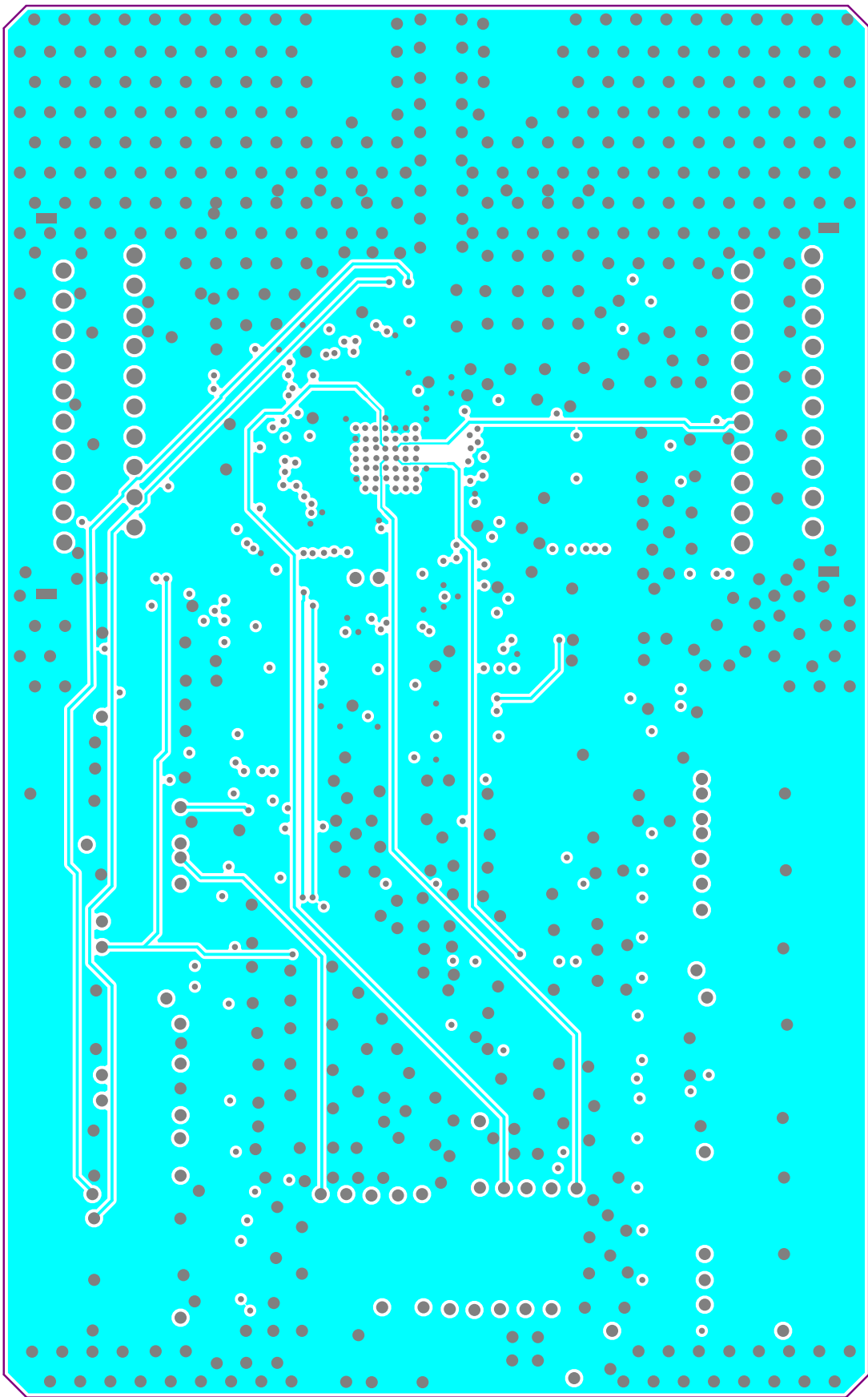
Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: Int2 (Sign)	Gerber: .G2	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	




Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: Int3 (Sign)	Gerber: .G3	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	

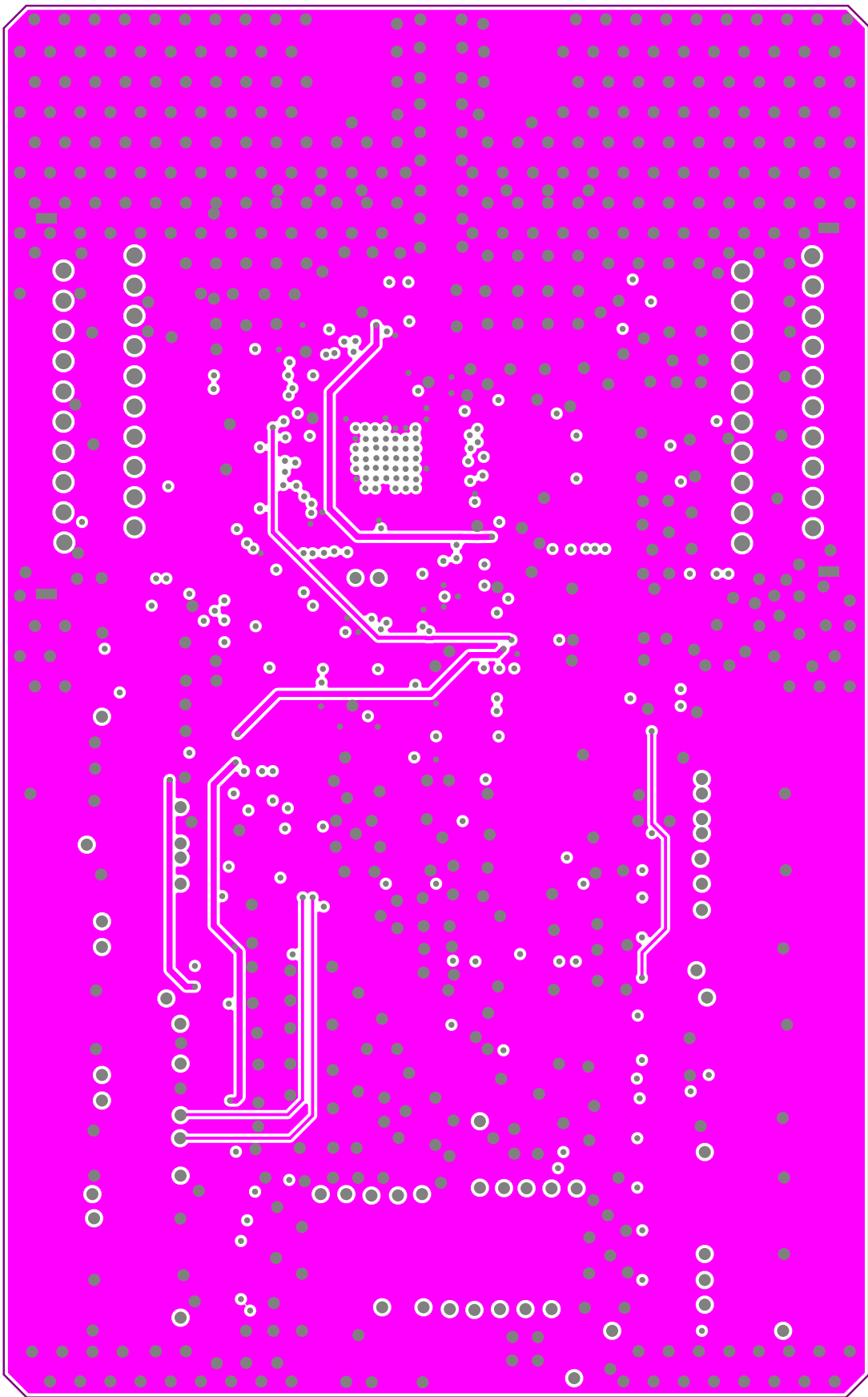



Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: <a href="#">Int4 (Sign)</a>	Gerber: <a href="#">.G4</a>	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	

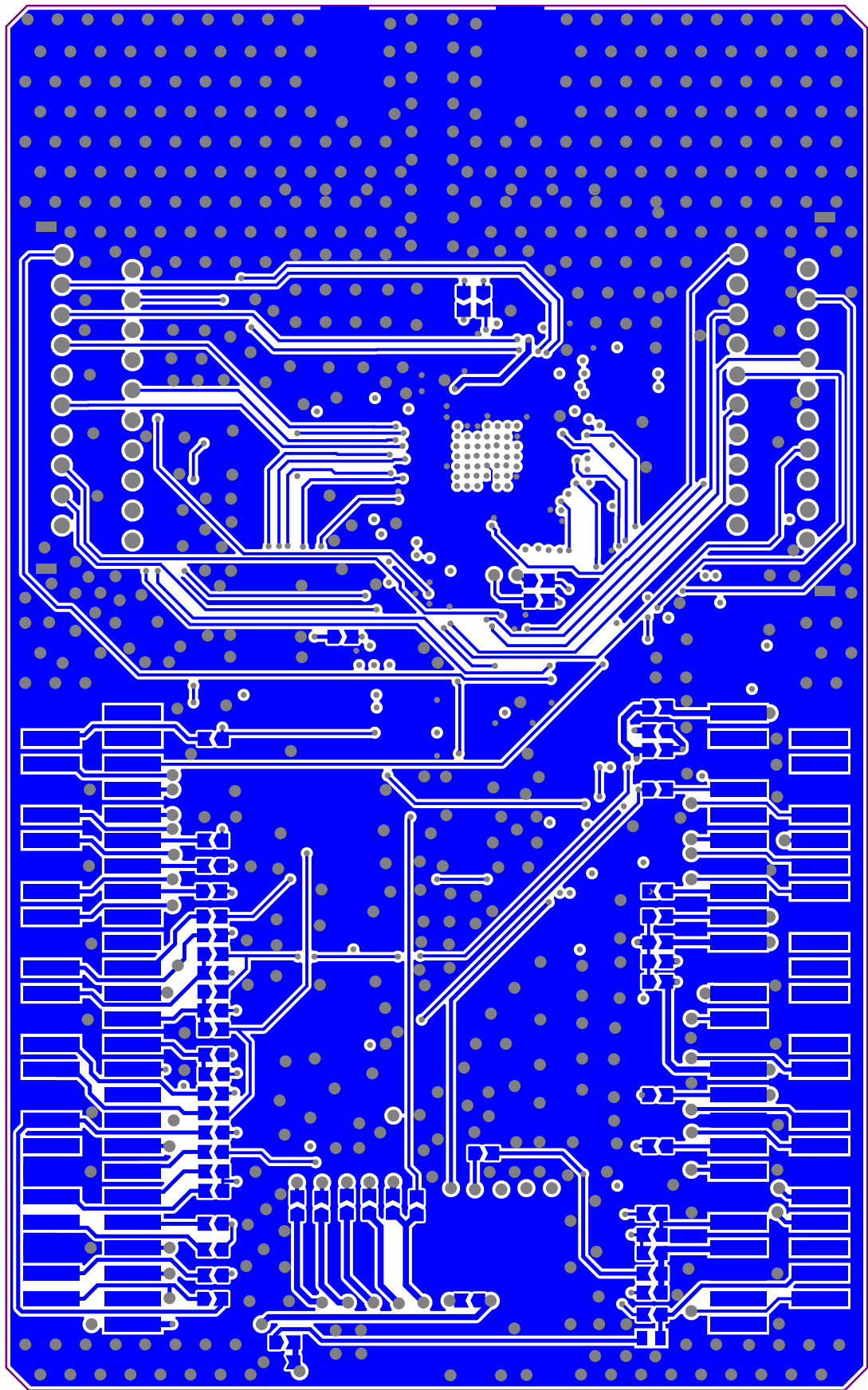



Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: Int5 (Sign)	Gerber: .G5	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	

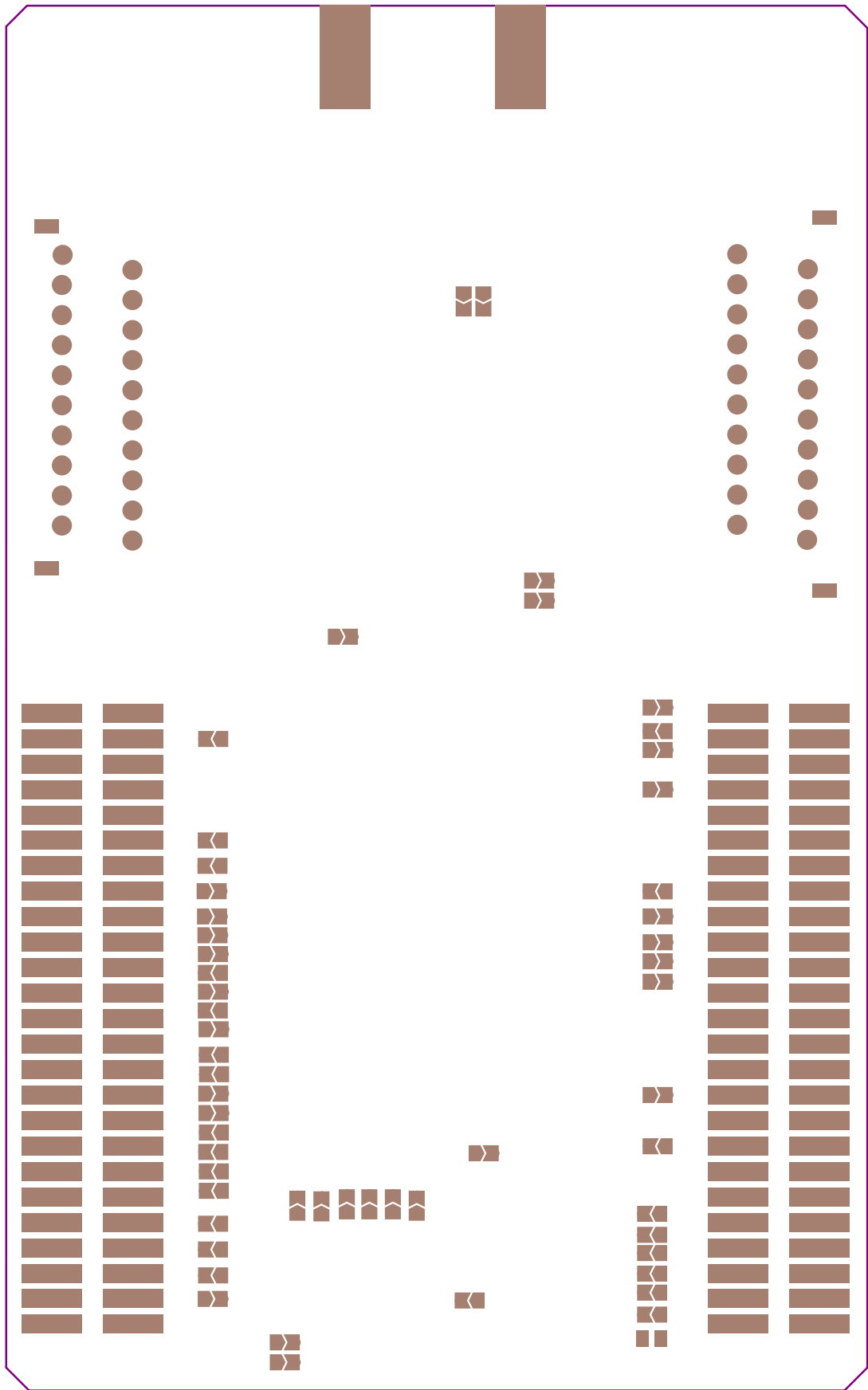





Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: Int6 (Sign)	Gerber: .G6	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	



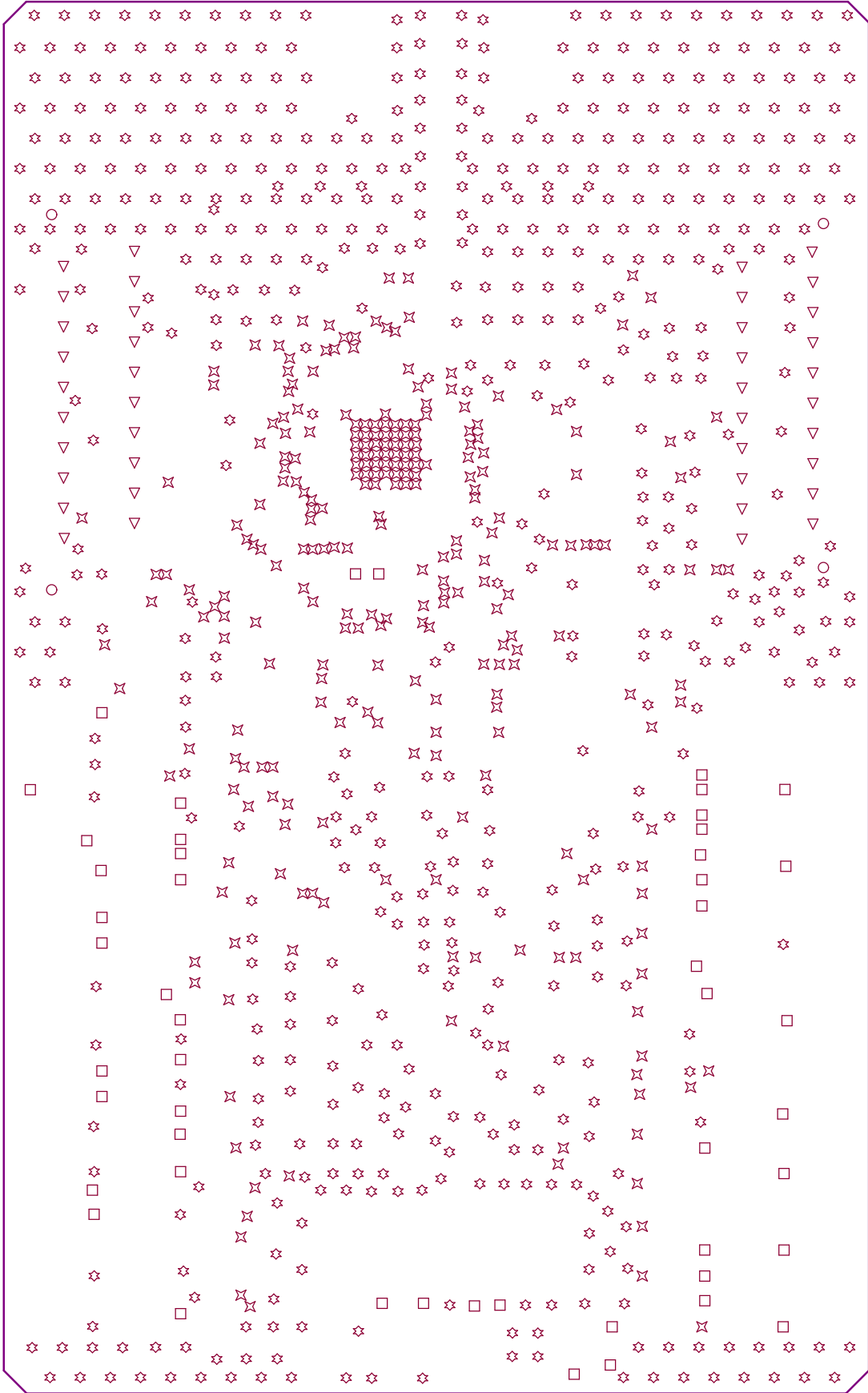
Project: MB2371_Miniboard_STM32WBA62PII6_BGA121_LDO		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	




Project: MB2371_Miniboard_STM32WBA62PII6_BGA121_LDO		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	1.00mil	4	
	Top Surface Finish	PbSn	0.79mil		
1	Top Layer	CF-004	1.38mil		
	Dielectric 1	PP-006	2.80mil	4.1	
2	Int1 (Sign)	CF-004	1.38mil		
	Dielectric 6	PP-006	2.80mil	4.1	
3	Int2 (Sign)	CF-004	1.38mil		
	Dielectric 2	Core-035	18.00mil	4.7	
4	Int3 (Sign)	CF-004	1.38mil		
	Dielectric 3	Core-028	10.00mil	4.3	
5	Int4 (Sign)	CF-004	1.38mil		
	Dielectric 4	Core-035	18.00mil	4.7	
6	Int5 (Sign)	CF-004	1.38mil		
	Dielectric 7	PP-006	2.80mil	4.1	
7	Int6 (Sign)	CF-004	1.38mil		
	Dielectric 5	PP-006	2.80mil	4.1	
8	Bottom Layer	CF-004	1.38mil		
	Bottom Surface Finish	PbSn	0.79mil		
	Bottom Solder	SM-001	1.00mil	4	
	Bottom Overlay				



Project: MB2371_Miniboard_STM32WBA62PII6_BGA121 LDO		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB2371	
Date: 03-12-2024	Rev: A	